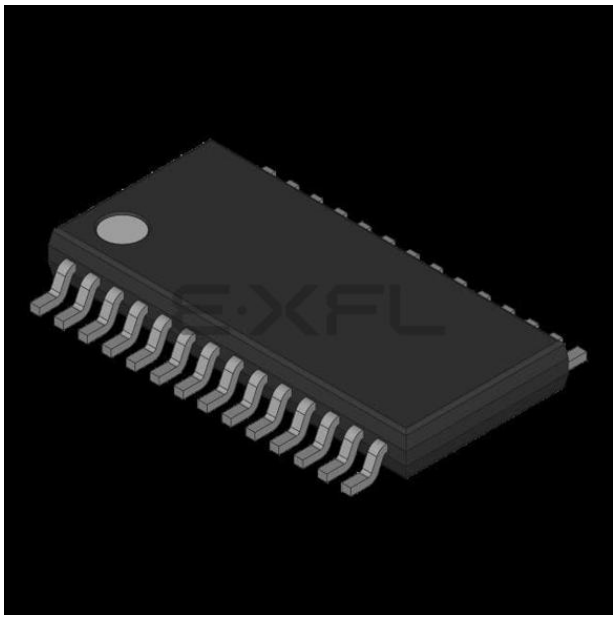

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Details	
Product Status	Active
Core Processor	HC08
Core Size	8-Bit
Speed	8MHz
Connectivity	SCI, SPI
Peripherals	LVD, POR, PWM
Number of I/O	24
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	28-TSSOP (0.173", 4.40mm Width)
Supplier Device Package	28-TSSOP
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The following revision history table summarizes changes contained in this document. For your convenience, the page number designators have been linked to the appropriate location.

Revision History

Date	Revision Level	Description	Page Number(s)
April, 2006	1.0	Initial release	N/A
May, 2006	1.1	19.5 5-V DC Electrical Characteristics — Updated values	237
		19.8 3.3-V DC Electrical Characteristics — Updated values	240
		19.11 Oscillator Characteristics — Updated values	243
		Figure 19-9. Typical 5-Volt Run Current versus Bus Frequency (25 C) and Figure 19-10. Typical 3.3-Volt Run Current versus Bus Frequency (25 C) — added	247
October, 2006	2.0	1.7 Unused Pin Termination — Added new section	24
		11.2 Unused Pin Termination — Replaced note with new section	107
		19.5 5-V DC Electrical Characteristics — New values for: DC injection current Low-voltage inhibit reset, trip rising voltage	237
		19.8 3.3-V DC Electrical Characteristics — New values for: DC injection current Low-voltage inhibit reset, trip rising voltage	240
		19.12 Supply Current Characteristics — New values for stop mode supply currents at –40 to 125°C	246
		20.3 Package Dimensions — Updated package dimension drawing for the 28-lead TSSOP.	261
April, 2007	3.0	Table 1-2. Pin Functions — Added note	22
		Figure 2-2. Control, Status, and Data Registers — Corrected Port C Data Register bit PTC3	27
		Chapter 3 Analog-to-Digital Converter (ADC10) Module — Renamed ADCSC register to ADSCR to be consistent with development tools	45
		Chapter 4 Configuration Registers (CONFIG1 and CONFIG2) — Changed CGMXCLK to BUSCLKX4	60
		11.3 Port A — Added information to first paragraph of note	107
		11.3.1 Port A Data Register — Corrected bit designations for the first entry under Figure 11-1. Port A Data Register (PTA).	108
		11.5 Port C — Added note and corrected address location designation in last paragraph	112 113
		Chapter 13 Enhanced Serial Communications Interface (ESCI) Module — Changed SCIBDSRC to ESCIBDSRC and CGMXCLK to BUSCLKX4	123
		13.9.3 Bit Time Measurement — Corrected first sentence of listing number 1	150
		Figure 18-18. Monitor Mode Entry Timing — Changed CGMXCLK to BUSCLKX4	234
October, 2007	4.0	In 19.12 Supply Current Characteristics, updated stop I_{DD} values	246
April, 2008	5.0	In 19.12 Supply Current Characteristics, reverted to Rev. 3 stop I_{DD} values	246

Chapter 2
Memory

2.1 Introduction

The central processor unit (CPU08) can address 64 Kbytes of memory space. The memory map is shown in Figure 2-1.

2.2 Unimplemented Memory Locations

Executing code from an unimplemented location will cause an illegal address reset. In Figure 2-1, unimplemented locations are shaded.

2.3 Reserved Memory Locations

Accessing a reserved location can have unpredictable effects on MCU operation. In Figure 2-1, reserved locations are marked with the word reserved or with the letter R.

2.4 Direct Page Registers

Figure 2-2 shows the memory mapped registers. Registers with addresses between $0000 and $00FF are considered direct page registers and all instructions including those with direct page addressing modes can access them. Registers between $0100 and $FFFF require non-direct page addressing modes. See Chapter 6 Central Processor Unit (CPU) for more information on addressing modes.

6.3.5 Condition Code Register

The 8-bit condition code register contains the interrupt mask and five flags that indicate the results of the instruction just executed. Bits 6 and 5 are set permanently to 1. The following paragraphs describe the functions of the condition code register.

	Bit 7	6	5	4	3	2	1	Bit 0
Read: Write:	V	1	1	H	I	N	Z	C
Reset:	X	1	1	X	1	X	X	X

X = Indeterminate

Figure 6-6. Condition Code Register (CCR)

V — Overflow Flag

The CPU sets the overflow flag when a two's complement overflow occurs. The signed branch instructions BGT, BGE, BLE, and BLT use the overflow flag.

1 = Overflow
0 = No overflow

H — Half-Carry Flag

The CPU sets the half-carry flag when a carry occurs between accumulator bits 3 and 4 during an add-without-carry (ADD) or add-with-carry (ADC) operation. The half-carry flag is required for binary-coded decimal (BCD) arithmetic operations. The DAA instruction uses the states of the H and C flags to determine the appropriate correction factor.

1 = Carry between bits 3 and 4
0 = No carry between bits 3 and 4

I — Interrupt Mask

When the interrupt mask is set, all maskable CPU interrupts are disabled. CPU interrupts are enabled when the interrupt mask is cleared. When a CPU interrupt occurs, the interrupt mask is set automatically after the CPU registers are saved on the stack, but before the interrupt vector is fetched.

1 = Interrupts disabled
0 = Interrupts enabled

NOTE

To maintain M6805 Family compatibility, the upper byte of the index register (H) is not stacked automatically. If the interrupt service routine modifies H, then the user must stack and unstack H using the PSHH and PULH instructions.

After the I bit is cleared, the highest-priority interrupt request is serviced first.

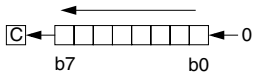
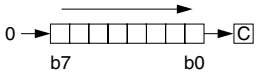
A return-from-interrupt (RTI) instruction pulls the CPU registers from the stack and restores the interrupt mask from the stack. After any reset, the interrupt mask is set and can be cleared only by the clear interrupt mask software instruction (CLI).

N — Negative Flag

The CPU sets the negative flag when an arithmetic operation, logic operation, or data manipulation produces a negative result, setting bit 7 of the result.

1 = Negative result
0 = Non-negative result

Table 6-1. Instruction Set Summary (Sheet 4 of 6)

Source Form	Operation	Description	Effect on CCR						Address Mode	Opcode	Operand	Cycles
			V	H	I	N	Z	C				
JMP *opr* JMP *opr* JMP *opr*,X JMP *opr*,X JMP ,X	Jump	PC ← Jump Address	–	–	–	–	–	–	DIR EXT IX2 IX1 IX	BC CC DC EC FC	dd hh ll ee ff ff	2 3 4 3 2
JSR *opr* JSR *opr* JSR *opr*,X JSR *opr*,X JSR ,X	Jump to Subroutine	PC ← (PC) + *n* (*n* = 1, 2, or 3) Push (PCL); SP ← (SP) – 1 Push (PCH); SP ← (SP) – 1 PC ← Unconditional Address	–	–	–	–	–	–	DIR EXT IX2 IX1 IX	BD CD DD ED FD	dd hh ll ee ff ff	4 5 6 5 4
LDA #*opr* LDA *opr* LDA *opr* LDA *opr*,X LDA *opr*,X LDA ,X LDA *opr*,SP LDA *opr*,SP	Load A from M	A ← (M)	0	–	–	↕	↕	–	IMM DIR EXT IX2 IX1 IX SP1 SP2	A6 B6 C6 D6 E6 F6 9EE6 9ED6	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
LDHX #*opr* LDHX *opr*	Load H:X from M	H:X ← (M:M + 1)	0	–	–	↕	↕	–	IMM DIR	45 55	ii jj dd	3 4
LDX #*opr* LDX *opr* LDX *opr* LDX *opr*,X LDX *opr*,X LDX ,X LDX *opr*,SP LDX *opr*,SP	Load X from M	X ← (M)	0	–	–	↕	↕	–	IMM DIR EXT IX2 IX1 IX SP1 SP2	AE BE CE DE EE FE 9EEE 9EDE	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
LSL *opr* LSLA LSLX LSL *opr*,X LSL ,X LSL *opr*,SP	Logical Shift Left (Same as ASL)		↕	–	–	↕	↕	↕	DIR INH INH IX1 IX SP1	38 48 58 68 78 9E68	dd ff ff	4 1 1 4 3 5
LSR *opr* LSRA LSR*X* LSR *opr*,X LSR ,X LSR *opr*,SP	Logical Shift Right		↕	–	–	0	↕	↕	DIR INH INH IX1 IX SP1	34 44 54 64 74 9E64	dd ff ff	4 1 1 4 3 5
MOV *opr*,*opr* MOV *opr*,X+ MOV #*opr*,*opr* MOV X+,*opr*	Move	$(M)_{Destination} \leftarrow (M)_{Source}$ H:X ← (H:X) + 1 (IX+D, DIX+)	0	–	–	↕	↕	–	DD DIX+ IMD IX+D	4E 5E 6E 7E	dd dd dd ii dd dd	5 4 4 4
MUL	Unsigned multiply	X:A ← (X) × (A)	–	0	–	–	–	0	INH	42		5
NEG *opr* NEGA NEGX NEG *opr*,X NEG ,X NEG *opr*,SP	Negate (Two's Complement)	M ← –(M) = $00 – (M) A ← –(A) = $00 – (A) X ← –(X) = $00 – (X) M ← –(M) = $00 – (M) M ← –(M) = $00 – (M)	↕	–	–	↕	↕	↕	DIR INH INH IX1 IX SP1	30 40 50 60 70 9E60	dd ff ff	4 1 1 4 3 5
NOP	No Operation	None	–	–	–	–	–	–	INH	9D		1
NSA	Nibble Swap A	A ← (A[3:0]:A[7:4])	–	–	–	–	–	–	INH	62		3
ORA #*opr* ORA *opr* ORA *opr* ORA *opr*,X ORA *opr*,X ORA ,X ORA *opr*,SP ORA *opr*,SP	Inclusive OR A and M	A ← (A) | (M)	0	–	–	↕	↕	–	IMM DIR EXT IX2 IX1 IX SP1 SP2	AA BA CA DA EA FA 9EEA 9EDA	ii dd hh ll ee ff ff ff ee ff	2 3 4 4 3 2 4 5
PSHA	Push A onto Stack	Push (A); SP ← (SP) – 1	–	–	–	–	–	–	INH	87		2
PSHH	Push H onto Stack	Push (H); SP ← (SP) – 1	–	–	–	–	–	–	INH	8B		2
PSHX	Push X onto Stack	Push (X); SP ← (SP) – 1	–	–	–	–	–	–	INH	89		2

7.3.2 MODE = 0

If the MODE bit is clear, the $\overline{IRQ}$ pin is falling edge sensitive only. With MODE clear, an IRQ vector fetch or software clear immediately clears the IRQ latch.

The IRQF bit in INTSCR can be read to check for pending interrupts. The IRQF bit is not affected by IMASK, which makes it useful in applications where polling is preferred.

NOTE

When using the level-sensitive interrupt trigger, avoid false IRQ interrupts by masking interrupt requests in the interrupt routine.

7.4 Interrupts

The following IRQ source can generate interrupt requests:

- Interrupt flag (IRQF) — The IRQF bit is set when the $\overline{IRQ}$ pin is asserted based on the IRQ mode. The IRQ interrupt mask bit, IMASK, is used to enable or disable IRQ interrupt requests.

7.5 Low-Power Modes

The WAIT and STOP instructions put the MCU in low power-consumption standby modes.

7.5.1 Wait Mode

The IRQ module remains active in wait mode. Clearing IMASK in INTSCR enables IRQ interrupt requests to bring the MCU out of wait mode.

7.5.2 Stop Mode

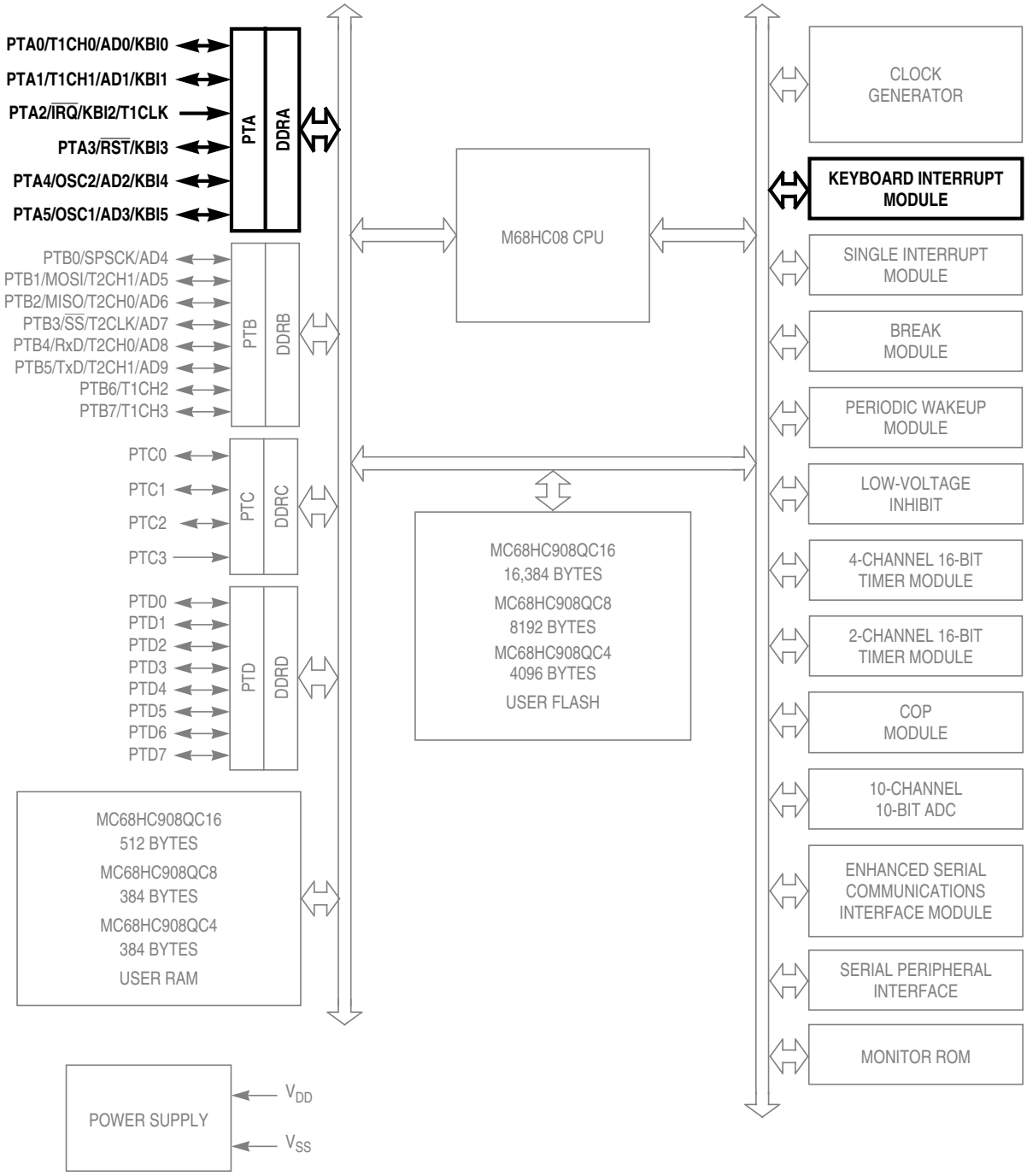
The IRQ module remains active in stop mode. Clearing IMASK in INTSCR enables IRQ interrupt requests to bring the MCU out of stop mode.

7.6 IRQ Module During Break Interrupts

The system integration module (SIM) controls whether status bits in other modules can be cleared during the break state. The BCFE bit in the break flag control register (BFCR) enables software to clear status bits during the break state. See BFCR in the SIM section of this data sheet.

To allow software to clear status bits during a break interrupt, write a 1 to BCFE. If a status bit is cleared during the break state, it remains cleared when the MCU exits the break state.

To protect status bits during the break state, write a 0 to BCFE. With BCFE cleared (its default state), software can read and write registers during the break state without affecting status bits. Some status bits have a two-step read/write clearing procedure. If software does the first step on such a bit before the break, the bit cannot change during the break state as long as BCFE is cleared. After the break, doing the second step clears the status bit.



All port pins can be configured with internal pullup
PTC not available on 16-pin devices (see note in 11.1 Introduction)
PTD not available on 16-pin or 20-pin devices (see note in 11.1 Introduction)

Figure 8-2. Block Diagram Highlighting KBI Block and Pins

10.3.1.2 XTAL Oscillator Clock (XTALCLK)

XTALCLK is the XTAL oscillator output signal. It runs at the full speed of the crystal (f_{XCLK}) and comes directly from the crystal oscillator circuit. Figure 10-2 shows only the logical relation of XTALCLK to OSC1 and OSC2 and may not represent the actual circuitry. The duty cycle of XTALCLK is unknown and may depend on the crystal and other external factors. The frequency of XTALCLK can be unstable at start up.

10.3.1.3 RC Oscillator Clock (RCCLK)

RCCLK is the RC oscillator output signal. Its frequency is directly proportional to the time constant of the external R (R_{EXT}) and internal C. Figure 10-3 shows only the logical relation of RCCLK to OSC1 and may not represent the actual circuitry.

10.3.1.4 Internal Oscillator Clock (INTCLK)

INTCLK is the internal oscillator output signal. INTCLK is software selectable to be nominally 25.6 MHz, 12.8 MHz, 8.0 MHz, or 4.0 MHz. INTCLK can be digitally adjusted using the oscillator trimming feature of the OSCTRIM register (see 10.3.2.1 Internal Oscillator Trimming).

10.3.1.5 Bus Clock Times 4 (BUSCLKX4)

BUSCLKX4 is the same frequency as the input clock (XTALCLK, RCCLK, or INTCLK). This signal is driven to the SIM module and is used during recovery from reset and stop and is the clock source for the COP module.

10.3.1.6 Bus Clock Times 2 (BUSCLKX2)

The frequency of this signal is equal to half of the BUSCLKX4. This signal is driven to the SIM for generation of the bus clocks used by the CPU and other modules on the MCU. BUSCLKX2 will be divided by two in the SIM. The internal bus frequency is one fourth of the XTALCLK, RCCLK, or INTCLK frequency.

10.3.2 Internal Oscillator

The internal oscillator circuit is designed for use with no external components to provide a clock source with a tolerance of less than 25%untrimmed. An 8-bit register (OSCTRIM) allows the digital adjustment to a tolerance of ACC_{INT}. See the oscillator characteristics in the Electrical section of this data sheet.

The internal oscillator is capable of generating clocks of 25.6 MHz, 12.8 MHz, 8.0 MHz, or 4.0 MHz (INTCLK) resulting in a bus frequency (INTCLK divided by 4) of 6.4 MHz, 3.2 MHz, 2.0 MHz, or 1.0 MHz respectively. The bus clock is software selectable and defaults to the 1.0-MHz bus out of reset. Users can increase the bus frequency based on the voltage range of their application.

Figure 10-3 shows how BUSCLKX4 is derived from INTCLK and OSC2 can output BUSCLKX4 by setting OSC2EN.

10.3.2.1 Internal Oscillator Trimming

OSCTRIM allows a clock period adjustment of +127 and –128 steps. Increasing the OSCTRIM value increases the clock period, which decreases the clock frequency. Trimming allows the internal clock frequency to be fine tuned to the target frequency.

All devices are factory programmed with a trim value that is stored in FLASH memory at location $FFC0. This trim value is not automatically loaded into OSCTRIM register. User software must copy the trim value

a valid character that sets the SCRF bit before an idle condition can set the IDLE bit. Also, after the IDLE bit has been cleared, a valid character must again set the SCRF bit before an idle condition can set the IDLE bit.

1 = Receiver input idle

0 = Receiver input active (or idle since the IDLE bit was cleared)

OR — Receiver Overrun Bit

This clearable, read-only bit is set when software fails to read the SCDR before the receive shift register receives the next character. The OR bit generates an ESCI error interrupt request if the ORIE bit in SCC3 is also set. The data in the shift register is lost, but the data already in the SCDR is not affected. Clear the OR bit by reading SCS1 with OR set and then reading the SCDR.

1 = Receive shift register full and SCRF = 1

0 = No receiver overrun

Software latency may allow an overrun to occur between reads of SCS1 and SCDR in the flag-clearing sequence. Figure 13-13 shows the normal flag-clearing sequence and an example of an overrun caused by a delayed flag-clearing sequence. The delayed read of SCDR does not clear the OR bit because OR was not set when SCS1 was read. Byte 2 caused the overrun and is lost. The next flag-clearing sequence reads byte 3 in the SCDR instead of byte 2.

In applications that are subject to software latency or in which it is important to know which byte is lost due to an overrun, the flag-clearing routine can check the OR bit in a second read of SCS1 after reading the data register.

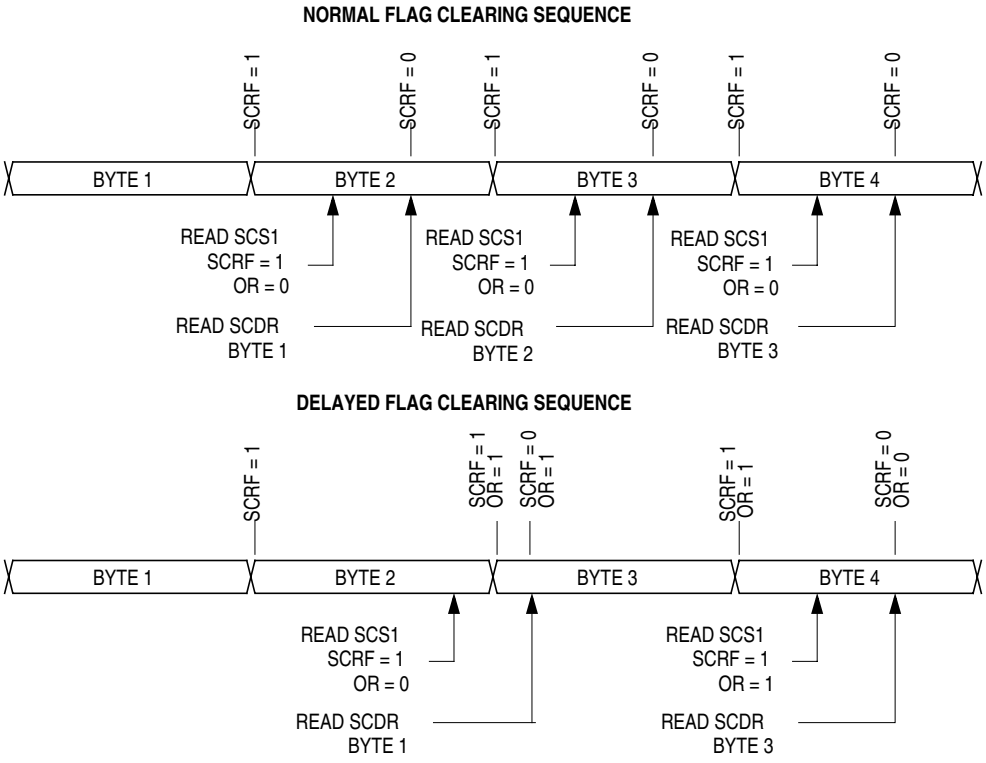


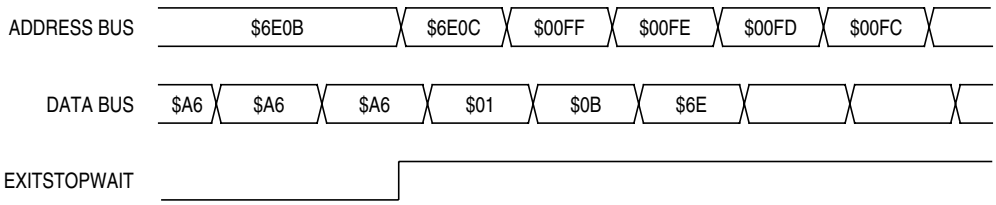
Figure 13-13. Flag Clearing Sequence

Table 13-10. ESCI Baud Rate Selection Examples

PDS[2:1:0]	PSSB[4:3:2:1:0]	SCP[1:0]	Prescaler Divisor (BPD)	SCR[2:1:0]	Baud Rate Divisor (BD)	Baud Rate (f_{Bus}= 4.9152 MHz)
0 0 0	X X X X X	0 0	1	0 0 0	1	76,800
1 1 1	0 0 0 0 0	0 0	1	0 0 0	1	9600
1 1 1	0 0 0 0 1	0 0	1	0 0 0	1	9562.65
1 1 1	0 0 0 1 0	0 0	1	0 0 0	1	9525.58
1 1 1	1 1 1 1 1	0 0	1	0 0 0	1	8563.07
0 0 0	X X X X X	0 0	1	0 0 1	2	38,400
0 0 0	X X X X X	0 0	1	0 1 0	4	19,200
0 0 0	X X X X X	0 0	1	0 1 1	8	9600
0 0 0	X X X X X	0 0	1	1 0 0	16	4800
0 0 0	X X X X X	0 0	1	1 0 1	32	2400
0 0 0	X X X X X	0 0	1	1 1 0	64	1200
0 0 0	X X X X X	0 0	1	1 1 1	128	600
0 0 0	X X X X X	0 1	3	0 0 0	1	25,600
0 0 0	X X X X X	0 1	3	0 0 1	2	12,800
0 0 0	X X X X X	0 1	3	0 1 0	4	6400
0 0 0	X X X X X	0 1	3	0 1 1	8	3200
0 0 0	X X X X X	0 1	3	1 0 0	16	1600
0 0 0	X X X X X	0 1	3	1 0 1	32	800
0 0 0	X X X X X	0 1	3	1 1 0	64	400
0 0 0	X X X X X	0 1	3	1 1 1	128	200
0 0 0	X X X X X	1 0	4	0 0 0	1	19,200
0 0 0	X X X X X	1 0	4	0 0 1	2	9600
0 0 0	X X X X X	1 0	4	0 1 0	4	4800
0 0 0	X X X X X	1 0	4	0 1 1	8	2400
0 0 0	X X X X X	1 0	4	1 0 0	16	1200
0 0 0	X X X X X	1 0	4	1 0 1	32	600
0 0 0	X X X X X	1 0	4	1 1 0	64	300
0 0 0	X X X X X	1 0	4	1 1 1	128	150
0 0 0	X X X X X	1 1	13	0 0 0	1	5908
0 0 0	X X X X X	1 1	13	0 0 1	2	2954
0 0 0	X X X X X	1 1	13	0 1 0	4	1477
0 0 0	X X X X X	1 1	13	0 1 1	8	739
0 0 0	X X X X X	1 1	13	1 0 0	16	369
0 0 0	X X X X X	1 1	13	1 0 1	32	185
0 0 0	X X X X X	1 1	13	1 1 0	64	92
0 0 0	X X X X X	1 1	13	1 1 1	128	46

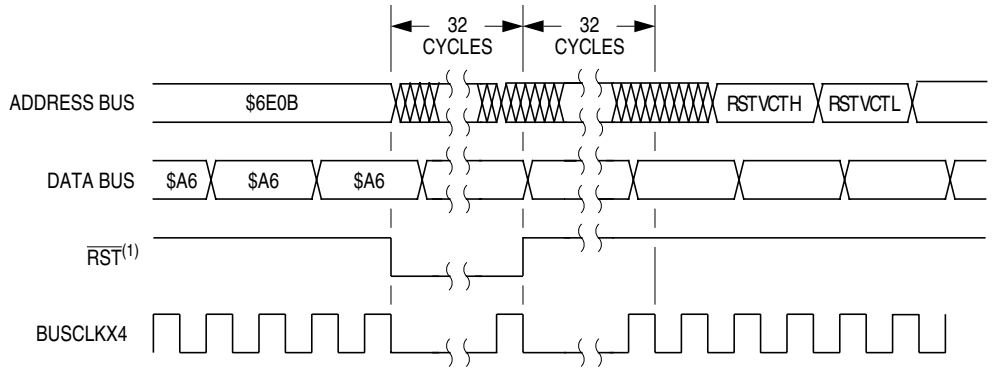
Wait mode can also be exited by a reset (or break in emulation mode). A break interrupt during wait mode sets the SIM break stop/wait bit, SBSW, in the break status register (BSR). If the COP disable bit, COPD, in the configuration register is 0, then the computer operating properly module (COP) is enabled and remains active in wait mode.

Figure 14-15 and Figure 14-16 show the timing for wait recovery.



NOTE: EXITSTOPWAIT = $\overline{\text{RST}}$ pin OR CPU interrupt

Figure 14-15. Wait Recovery from Interrupt



1. $\overline{\text{RST}}$ is only available if the RSTEN bit in the CONFIG2 register is set.

Figure 14-16. Wait Recovery from Internal Reset

14.7.2 Stop Mode

In stop mode, the SIM counter is reset and the system clocks are disabled. An interrupt request from a module can cause an exit from stop mode. Stacking for interrupts begins after the selected stop recovery time has elapsed. Reset or break also causes an exit from stop mode.

The SIM disables the oscillator signals (BUSCLKX2 and BUSCLKX4) in stop mode, stopping the CPU and peripherals. If OSCENINSTOP is set, BUSCLKX4 will remain running in STOP and can be used to run the PWU. Stop recovery time is selectable using the SSREC bit in the configuration register 1 (CONFIG1). If SSREC is set, stop recovery is reduced from the normal delay of 4096 BUSCLKX4 cycles down to 32. This is ideal for the internal oscillator, RC oscillator, and external oscillator options which do not require long start-up times from stop mode.

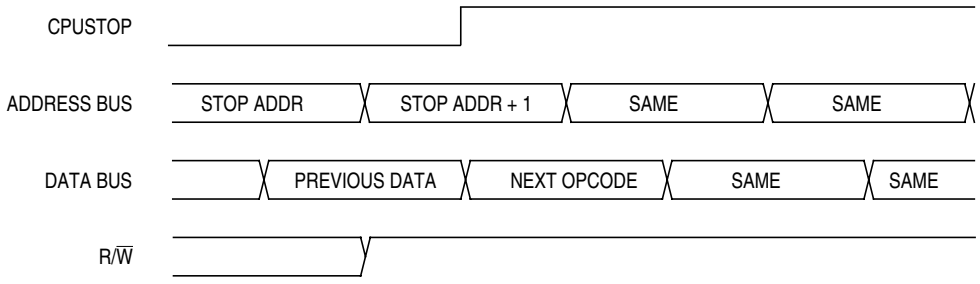
NOTE

External crystal applications should use the full stop recovery time by clearing the SSREC bit.

The SIM counter is held in reset from the execution of the STOP instruction until the beginning of stop recovery. It is then used to time the recovery period. Figure 14-17 shows stop mode entry timing and Figure 14-18 shows the stop mode recovery time from interrupt or break

NOTE

To minimize stop current, all pins configured as inputs should be driven to a logic 1 or logic 0.



NOTE: Previous data can be operand data or the STOP opcode, depending on the last instruction.

Figure 14-17. Stop Mode Entry Timing

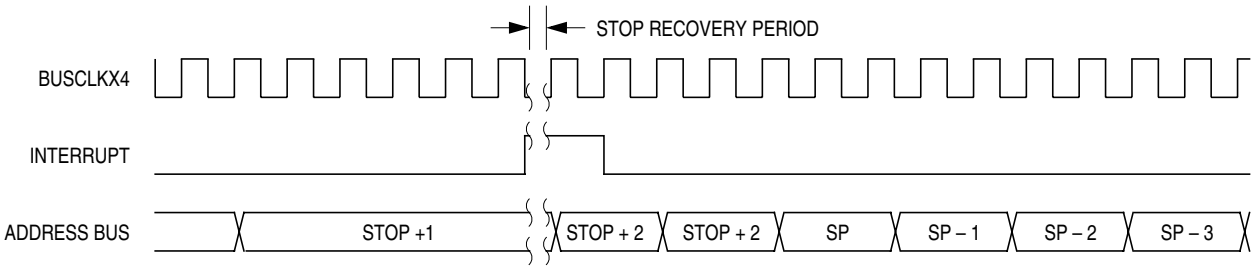


Figure 14-18. Stop Mode Recovery from Interrupt

14.8 SIM Registers

The SIM has three memory mapped registers. Table 14-4 shows the mapping of these registers.

Table 14-4. SIM Registers

Address	Register	Access Mode
$FE00	BSR	User
$FE01	SRSR	User
$FE03	BFCR	User

output after the TIM1 overflows. At each subsequent overflow, the TIM1 channel registers (0 or 1) that control the output are the ones written to last. T1SC0 controls and monitors the buffered output compare function, and TIM1 channel 1 status and control register (T1SC1) is unused. While the MS0B bit is set, the channel 1 pin, T1CH1, is available as a general-purpose I/O pin.

Channels 2 and 3 can be linked to form a buffered output compare channel whose output appears on the T1CH2 pin. The TIM1 channel registers of the linked pair alternately control the output.

Setting the MS2B bit in TIM1 channel 2 status and control register (T1SC2) links channel 2 and channel 3. The output compare value in the TIM1 channel 2 registers initially controls the output on the T1CH2 pin. Writing to the TIM1 channel 3 registers enables the TIM1 channel 3 registers to synchronously control the output after the TIM1 overflows. At each subsequent overflow, the TIM1 channel registers (2 or 3) that control the output are the ones written to last. T1SC2 controls and monitors the buffered output compare function, and TIM1 channel 3 status and control register (T1SC3) is unused. While the MS2B bit is set, the channel 3 pin, T1CH3, is available as a general-purpose I/O pin.

NOTE

In buffered output compare operation, do not write new output compare values to the currently active channel registers. User software should track the currently active channel to prevent writing a new value to the active channel. Writing to the active channel registers is the same as generating unbuffered output compares.

16.3.4 Pulse Width Modulation (PWM)

By using the toggle-on-overflow feature with an output compare channel, the TIM1 can generate a PWM signal. The value in the TIM1 counter modulo registers determines the period of the PWM signal. The channel pin toggles when the counter reaches the value in the TIM1 counter modulo registers. The time between overflows is the period of the PWM signal.

As Figure 16-3 shows, the output compare value in the TIM1 channel registers determines the pulse width of the PWM signal. The time between overflow and output compare is the pulse width. Program the TIM1 to clear the channel pin on output compare if the polarity of the PWM pulse is 1 (ELSxA = 0). Program the TIM1 to set the pin if the polarity of the PWM pulse is 0 (ELSxA = 1).

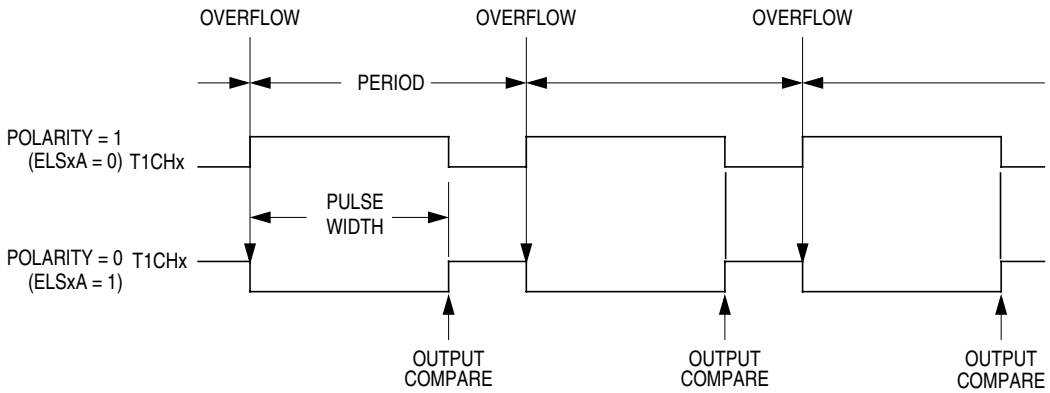


Figure 16-3. PWM Period and Pulse Width

Table 18-2. Mode Difference

Modes	Functions					
	Reset Vector High	Reset Vector Low	Break Vector High	Break Vector Low	SWI Vector High	SWI Vector Low
User	$FFFE	$FFFF	$FFFC	$FFFD	$FFFC	$FFFD
Monitor	$FEFE	$FEFF	$FEFC	$FEFD	$FEFC	$FEFD

18.3.1.4 Data Format

Communication with the monitor ROM is in standard non-return-to-zero (NRZ) mark/space data format. Transmit and receive baud rates must be identical.

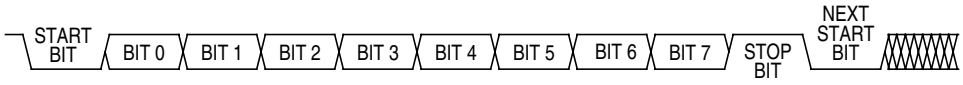


Figure 18-13. Monitor Data Format

18.3.1.5 Break Signal

A start bit (logic 0) followed by nine logic 0 bits is a break signal. When the monitor receives a break signal, it drives the PTA0 pin high for the duration of two bits and then echoes back the break signal.

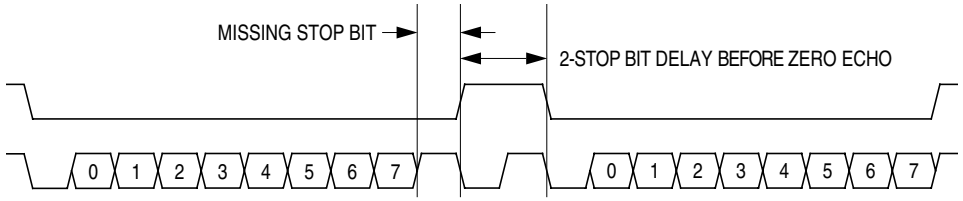


Figure 18-14. Break Transaction

18.3.1.6 Baud Rate

The monitor communication baud rate is controlled by the frequency of the external or internal oscillator and the state of the appropriate pins as shown in Table 18-1.

Table 18-1 also lists the bus frequencies to achieve standard baud rates. The effective baud rate is the bus frequency divided by 256 when using an external oscillator. When using the internal oscillator in forced monitor mode, the effective baud rate is the bus frequency divided by 335.

18.3.1.7 Commands

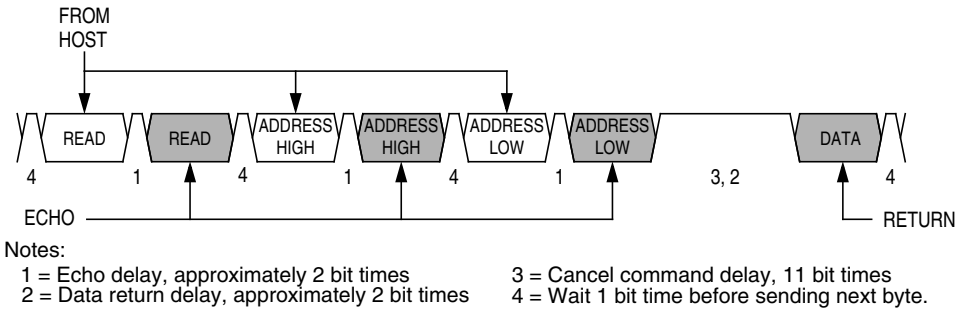
The monitor ROM firmware uses these commands:

- READ (read memory)
- WRITE (write memory)
- IREAD (indexed read)
- IWRITE (indexed write)
- READSP (read stack pointer)
- RUN (run user program)

The monitor ROM firmware echoes each received byte back to the PTA0 pin for error checking. An 11-bit delay at the end of each command allows the host to send a break character to cancel the command. A delay of two bit times occurs before each echo and before READ, IREAD, or READSP data is returned. The data returned by a read command appears after the echo of the last byte of the command.

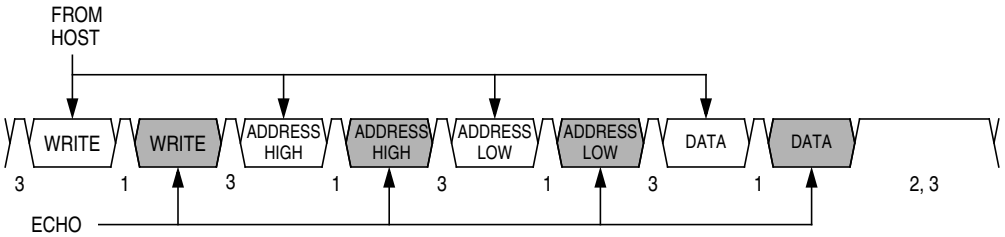
NOTE

Wait one bit time after each echo before sending the next byte.



Notes:
1 = Echo delay, approximately 2 bit times
2 = Data return delay, approximately 2 bit times
3 = Cancel command delay, 11 bit times
4 = Wait 1 bit time before sending next byte.

Figure 18-15. Read Transaction



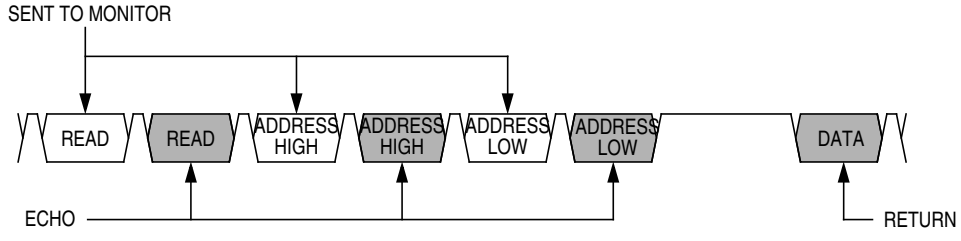
Notes:
1 = Echo delay, approximately 2 bit times
2 = Cancel command delay, 11 bit times
3 = Wait 1 bit time before sending next byte.

Figure 18-16. Write Transaction

A brief description of each monitor mode command is given in Table 18-3 through Table 18-8.

Table 18-3. READ (Read Memory) Command

Description	Read byte from memory
Operand	2-byte address in high-byte:low-byte order
Data Returned	Returns contents of specified address
Opcode	$4A
Command Sequence	



Chapter 19
Electrical Specifications

19.1 Introduction

This section contains electrical and timing specifications.

19.2 Absolute Maximum Ratings

Maximum ratings are the extreme limits to which the microcontroller unit (MCU) can be exposed without permanently damaging it.

NOTE

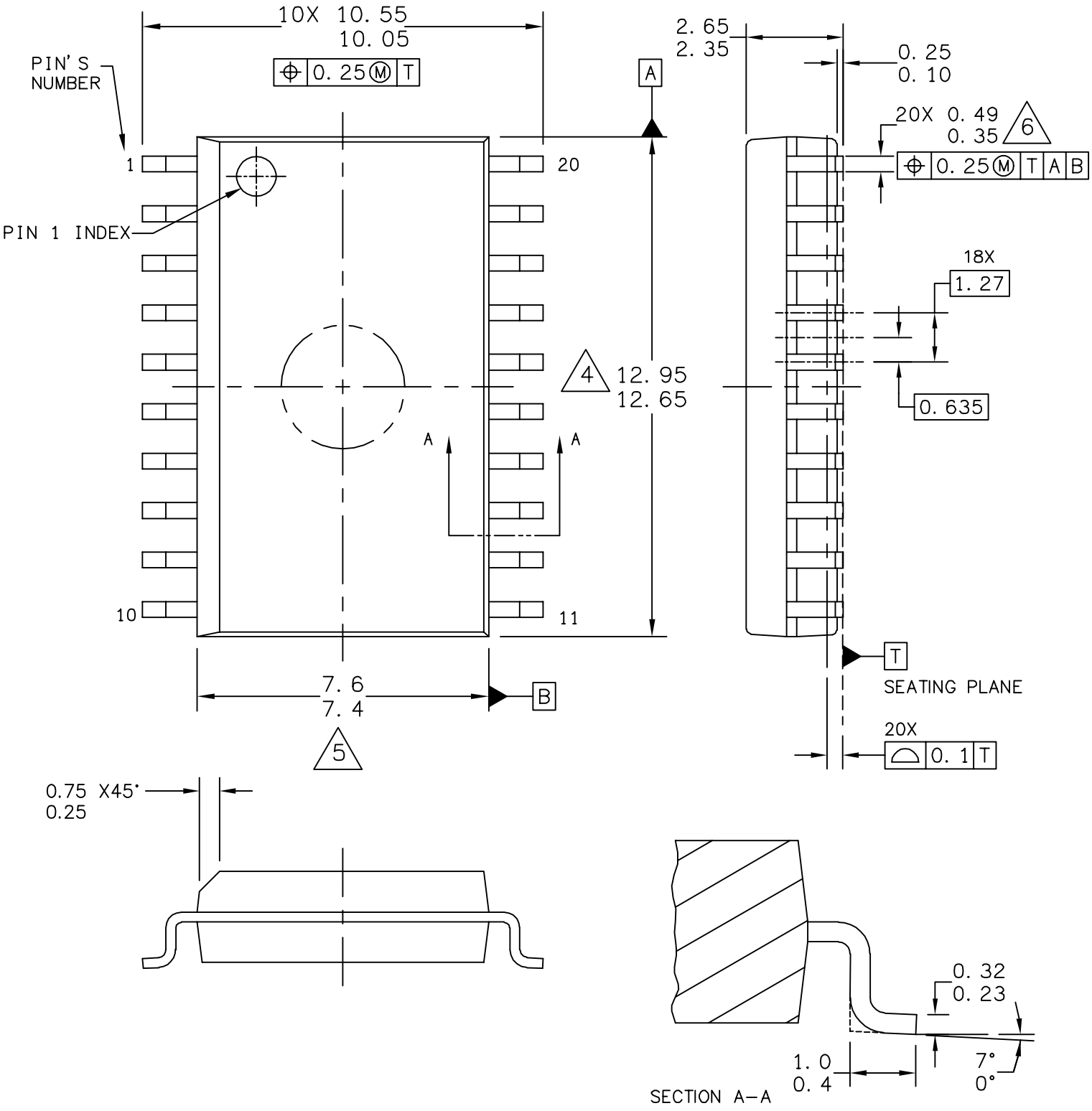
This device is not guaranteed to operate properly at the maximum ratings. Refer to 19.5 5-V DC Electrical Characteristics and 19.8 3.3-V DC Electrical Characteristics for guaranteed operating conditions.

Characteristic[1]	Symbol	Value	Unit
Supply voltage	V_{DD}	−0.3 to +6.0	V
Input voltage	V_{IN}	V_{SS} −0.3 to V_{DD} +0.3	V
Mode entry voltage, $\overline{IRQ}$ pin	V_{TST}	V_{SS} −0.3 to +9.1	V
Maximum current per pin excluding PTA0–PTA5, V_{DD}, and V_{SS}	I	±15	mA
Maximum current for pins PTA0–PTA5	I_{PTA0}—I_{PTA5}	±25	mA
Storage temperature	T_{STG}	−55 to +150	°C
Maximum current out of V_{SS}	I_{MVSS}	100	mA
Maximum current into V_{DD}	I_{MVDD}	100	mA

1. Voltages references to V_{SS}.

NOTE

This device contains circuitry to protect the inputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than maximum-rated voltages to this high-impedance circuit. For proper operation, it is recommended that V_{IN} and V_{OUT} be constrained to the range $V_{SS} \le (V_{IN}$ or $V_{OUT}) \le V_{DD}$. Reliability of operation is enhanced if unused inputs are connected to an appropriate logic voltage level (for example, either V_{SS} or V_{DD}.)



MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE:	DOCUMENT NO: 98ASB42343B	REV: J
20LD SOIC W/B, 1.27 PITCH CASE-OUTLINE	CASE NUMBER: 751D-07	23 MAR 2005
	STANDARD: JEDEC MS-013AC	

NOTES:

1. CONTROLLING DIMENSION: MILLIMETER

2. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M-1982.

3. DIMENSION DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 PER SIDE.

4. DIMENSION DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 PER SIDE.

5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF THE DIMENSION AT MAXIMUM MATERIAL CONDITION.

6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

7. DIMENSIONS ARE TO BE DETERMINED AT DATUM PLANE -W-.

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE:	DOCUMENT NO: 98ASH70169A	REV: C
20 LD TSSOP, PITCH 0.65MM	CASE NUMBER: 948E-02	25 MAY 2005
	STANDARD: JEDEC	